

05-07-2003



To the honorable Commission.

102441899

Attached original documents or copy thereof.

1. Name of conveying party(ies): Yee-Chia Yeo How-Yu Chen Chien-Chao Huang Wen-Chin Lee Fu-Liang Yang Chenming Hu

4-30-03

2. Name and address of receiving party(ies) Name: Taiwan Semiconductor Manufacturing Company, Ltd. Internal Address: Street Address: No. 6, Li-Hsin Rd. 6 Science-Based Industrial Park City: Hsin-Chu State: Taiwan Zip: 300-77

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance: [X] Assignment [] Merger [] Security Agreement [] Change of Name [] Other Execution Date: April 28, 2003

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s): 10426566 If this document is being filed together with a new application, the execution date of the application is: April 28, 2003 A. Patent Application No.(s) B. Patent No.(s) Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Steven H. Slater Slater & Matsil, L.L.P. Street Address: 17950 Preston Rd. Suite 1000 City: Dallas State: Texas Zip: 75252-5793

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41). \$ 40.00 [] Enclosed [X] Authorized to be charged to deposit account 8. Deposit account number: 50-1065 (Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Ira S. Matsil Reg. No. 35,272 Name of Person Signing Signature April 30, 2003 Date Total number of pages including cover sheet, attachments, and documents: 3

JP997 U.S. PTO 10/426566 04/30/03

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Mail Stop Assignments, P. O. Box 1450, Alexandria, VA 22313-1450

05/06/2003 6TON11 00000171 501065 10426566 01 FC:8021 40.00 CH

PATENT REEL: 014024 FRAME: 0545

ATTORNEY DOCKET NO.
TSMC03-0111

ASSIGNMENT

WHEREAS, I, the undersigned Inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 6, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;


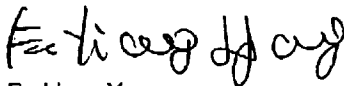
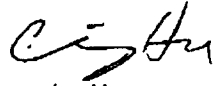
NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Semiconductor-on-Insulator Chip Incorporating Strained-Channel Partially-Depleted, Fully-Depleted, and Multiple-Gate Transistors		
SIGNATURE OF INVENTOR AND NAME	<i>Yee-Chia Yeo</i> Yee-Chia Yeo	<i>How-Yu Chen</i> How-Yu Chen	<i>Chien-Chao Huang</i> Chien-Chao Huang
DATE	<i>April 28, 2003.</i>	<i>April 28, 2003</i>	<i>Apr. 28, 2003</i>
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan 300-7 R.O.C.	Kaohsiung, Taiwan 302 R.O.C.	Hsin-Chu, Taiwan R.O.C.

SIGNATURE OF INVENTOR AND NAME	 Wen-Chin Lee	 Fu-Liang Yang	 Chenming Hu
DATE	04/28/03	04/28/03	04/28/03
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan 300 R.O.C.	Hsin-Chu, Taiwan 300 R.O.C.	Hsin-Chu, Taiwan 300 R.O.C.